



YES-310TA Vapor Prime + Image Reversal Oven

Dual Function System for HMDS Application as well as Image Reversal

Specifications

Hardware	
Clean Room Compatibility	Class 10
Wafer Size	Up to 200mm
Capacity	8 cassettes 100mm wafers 2 cassettes 125mm wafers 2 cassettes 150mm wafers 1 cassette 200mm wafers <i>*The Image Reversal process generally reduces the cassette capacity by ½.</i>
Batch Throughput	2 load/hr vacuum bake/vapor prime 1 load/hr image reversal
Operation Temperature	Ambient to 160 °C
Interior Chamber Dimensions	30.48 cm (W) x 33.66 cm (D) x 30.48 cm (H) (12" x 13.25" x 12")
Overall System Dimensions	63.195 cm (W) x 50.17 cm (D) x 77.29 cm (H) (24.88" x 19.75" x 30.43")
Chamber Material	316L stainless steel, aluminum door plate
Process Gas Inputs	1 N ₂ vent gas, 1 ammonia, 1 vapor flask
Cleanliness	<5 x 1 micron particles per 150 mm wafer
Nitrogen Consumption	7 SCF per process
Software	
Number of Recipes	8 process recipes
Range of Exposure Time	0-999999 seconds
Resolution of Timer Setting	1 second
Performance	
Temperature Uniformity	±5°C after stabilization period
Additional	
Power Requirements	188-253VAC, 50/60Hz, 10 amps



Contact Us

When you're ready to run process tests, a demonstration can be arranged using your chemicals and samples. Call +1 925-373-8353 (worldwide), 1-888-YES-3637 (US toll free), or visit us online at www.yieldengineering.com.

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